

**Amendments to the Claims:** Please cancel claims 23-25 and 27-30 without prejudice to Applicants' right to pursue similar claims in continuation applications.

This listing of claims will replace all prior versions, and listings, of claims in this application.

**Listing of Claims:**

1-5. (Canceled)

6. (Previously presented) The method of claim 26, wherein the step of forming a first electrically conductive element on the device body comprises co-extruding a first electrically conductive element within the device body.

7. (Previously presented) The method of claim 26, wherein the step of forming a first electrically conductive element on the device body comprises electro-depositing a conductive material on a nonconductive portion of the device body.

8. (Previously presented) The method of claim 26, wherein the step of extruding the second cylindrical body layer comprises extruding the second cylindrical body layer over the first cylindrical body layer.

9. (Previously presented) The method of claim 26, wherein the step of forming a first electrode on the device body comprises the steps of:  
forming a groove on at least a portion of the device body;  
depositing conductive material within the groove in a shape of the first electrode; and  
in the event that a portion of the conductive material extends beyond an upper surface of the groove, removing the portion of conductive material.

10. (Original) The method of claim 9, wherein the step of forming a groove on at least a portion of the device body is performed simultaneously with the step of forming the device body.

11. (Previously presented) The method of claim 26, wherein the step of forming a first electrically conductive element on the device body comprises the steps of:

co-extruding electrically conductive material with the first cylindrical body layer; and  
removing a portion of the first cylindrical body layer to expose at least a portion of the electrically conductive material.

12. (Previously presented) The method of claim 26, wherein the step of forming a first electrically conductive element on the device body comprises:

coating a surface of the device body with an electrically conductive material; and  
selectively removing at least a portion of the electrically conductive material from the device body.

13. (Original) The method of claim 12, wherein the step of selectively removing at least a portion of the electrically conductive material from the device body comprises exposing at least a portion of the electrically conductive material to a chemical solvent.

14. (Original) The method of claim 12, wherein the step of selectively removing at least a portion of the electrically conductive material from the device body comprises vaporizing at least a portion of the electrically conductive material with a laser.

15. (Previously presented) The method of claim 26, wherein the step of forming a first electrically conductive element on the device body comprises extruding a conductive layer across at least a portion of the device body.

16. (Original) The method claim 15, further comprising:  
extruding a second device body longitudinally encasing the device body and  
extruded conductive layer; and  
extruding a second conductive layer across at least a portion of the second device  
body.
17. (Previously presented) The method of claim 26, wherein the step of forming a first  
electrically conductive element on the device body comprises:  
feeding wire from a spool to a mandrel under tension;  
positioning the wire with respect to an ultimate location along the device body means  
of the mandrel; and  
co-extruding the wire with the device body.
18. (Previously presented) The method of claim 26, wherein the step of forming a first  
electrically conductive element on the device body comprises:  
forming a groove on an exterior surface of the device body; and  
placing a wire within the groove.
19. (Original) The method of claim 16, further comprising the steps of:  
forming a tip structure; and  
affixing the tip structure to the device body.
20. (Original) The method of claim 19, wherein the step of forming a tip structure  
comprises:  
plating a metal electrode over a molded non-conductive tip shape;  
forming a via in the tip shape; and  
electrically connecting a trace to the metal electrode through the via.

21. (Previously presented) The method of claim 26, further comprising the step of affixing an adaptor to a distal end of the device body.

22. (Original) The method of claim 21, wherein the step of affixing an adapter to a distal end of the device body comprises:

aligning an adapter trace with the first electrically conductive element with an adapter trace; and

inserting a portion of the adapter into the distal end of the device body such that the adapter trace and electrically conductive element are operably connected.

23-25. (Canceled)

26. (Previously presented) A method of manufacturing a medical device comprising:  
forming a device body by extruding a first cylindrical body layer;  
extruding a second cylindrical body layer;  
placing the second body layer within the first body layer; and  
bonding the second body layer to the first body layer;  
forming a first electrically conductive element on the device body;  
forming a first electrode on the device body; and  
operably connecting the first electrode and the first electrically conductive element.

27-30. (Canceled)